Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A method of making a package, comprising:
preparing a tray that retains a desiccant;
providing one or more semiconductor devices on the tray;
heating the tray; and
sealing the tray in a moisture-proof container.

2. (Original) The method according to claim 1, wherein the tray and the desiccant retained therein are recovered after use.

3. (Original) A method of reusing a desiccant, comprising:
recovering a tray in which a desiccant is retained;
providing one or more semiconductor devices on the tray;
heating the tray ;
sealing the tray in a moisture-proof container.

4. (Withdrawn) A tray for containing semiconductor devices, comprising:
a plurality of pockets for accommodating one or more semiconductor devices that are coated or encapsulated in a capsule; and
a retainer that retains a desiccant,
wherein the tray sustains enough heat to substantially remove any moisture absorbed by the coating or by the capsule.

5. (Withdrawn) The tray according to claim 4, wherein the retainer includes a groove in which the desiccant is placed, and a cover to retain the desiccant in the groove.

6. (New) The method according to claim 1, wherein the tray includes a groove in which the desiccant is placed, and a cover to retain the desiccant in the groove.